

## N-Channel Super Trench Power MOSFET

### Description

The HMS1 EPEU U uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{DS(on)}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.

### Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

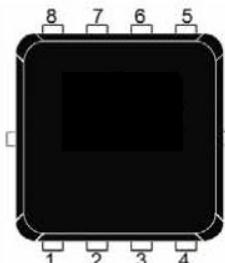
### General Features

- $V_{DS} = 60V, I_D = 10A$
- $R_{DS(on)} = 4.4m\Omega$  (typical) @  $V_{GS} = 10V$
- $R_{DS(on)} = 6.4m\Omega$  (typical) @  $V_{GS} = 4.5V$
- Excellent gate charge x  $R_{DS(on)}$  product(FOM)
- Very low on-resistance  $R_{DS(on)}$
- 150 °C operating temperature
- Pb-free lead plating

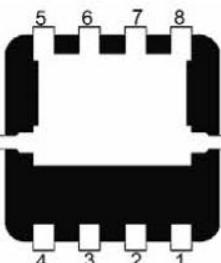
**100% UIS TESTED!**

**100% ΔVds TESTED!**

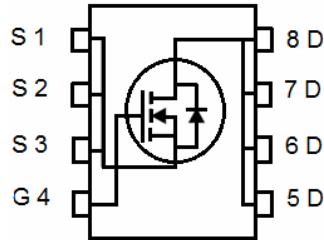
DFN 3.3X3.3



Top View



Bottom View



Schematic Diagram

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
HMS1 EPEU U	HMS1 EPEU U	DFN3.3X3.3-8L	-	-	-

### Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	10	A
Drain Current-Continuous( $T_c=100^\circ C$ )	$I_D(100^\circ C)$	8	A
Pulsed Drain Current	$I_{DM}$	10	A
Maximum Power Dissipation	$P_D$	60	W
Derating factor		0.48	W/°C
Single pulse avalanche energy <sup>(Note 5)</sup>	$E_{AS}$	350	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

### Thermal Characteristic

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	$R_{eJC}$	2.1	°C/W
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## **Electrical Characteristics ( $T_c=25^\circ\text{C}$ unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	60		-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=60V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>On Characteristics</b> (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.2	1.65	2.3	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=25A$	-	4.4	5.2	$m\Omega$
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=25A$	-	6.4	7.8	$m\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS}=5V, I_D=25A$		60	-	S
<b>Dynamic Characteristics</b> (Note 4)						
Input Capacitance	$C_{iss}$	$V_{DS}=30V, V_{GS}=0V, F=1.0MHz$	-	1600	-	PF
Output Capacitance	$C_{oss}$		-	320	-	PF
Reverse Transfer Capacitance	$C_{rss}$		-	9	-	PF
<b>Switching Characteristics</b> (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=30V, I_D=25A, V_{GS}=10V, R_G=1.6\Omega$	-	7	-	nS
Turn-on Rise Time	$t_r$		-	2	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	27	-	nS
Turn-Off Fall Time	$t_f$		-	4	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=30V, I_D=25A, V_{GS}=10V$	-	26	-	nC
Gate-Source Charge	$Q_{gs}$		-	8.3	-	nC
Gate-Drain Charge	$Q_{gd}$		-	5.5	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	$V_{SD}$	$V_{GS}=0V, I_S=25A$	-		1.2	V
Diode Forward Current (Note 2)	$I_S$		-	-	0	A
Reverse Recovery Time	$t_{rr}$	$T_J = 25^\circ C, I_F = 25A$ $di/dt = 100A/\mu s$ (Note 3)	-	38	-	nS
Reverse Recovery Charge	$Q_{rr}$		-	48	-	nC

## Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
  2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
  3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
  4. Guaranteed by design, not subject to production
  5. EAS condition :  $T_j=25^\circ C$ ,  $V_{DD}=30V$ ,  $V_G=10V$ ,  $L=0.5mH$ ,  $R_g=25\Omega$

### Typical Electrical and Thermal Characteristics

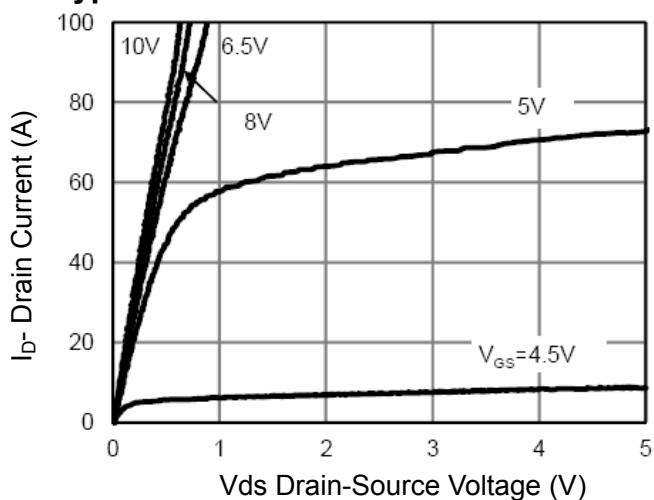


Figure 1 Output Characteristics

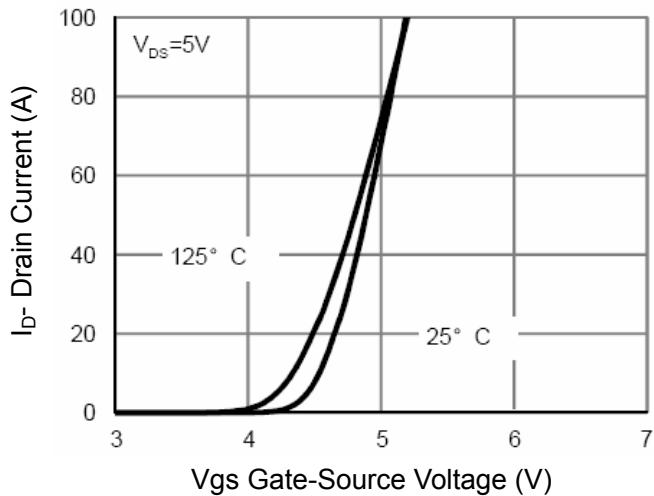


Figure 2 Transfer Characteristics

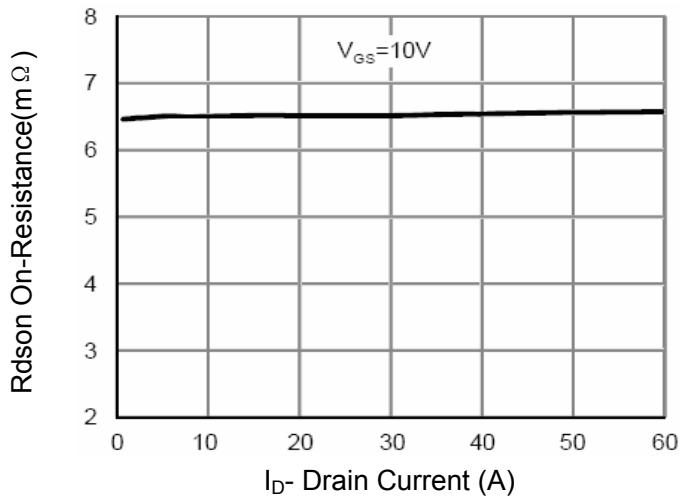


Figure 3 Rdson- Drain Current

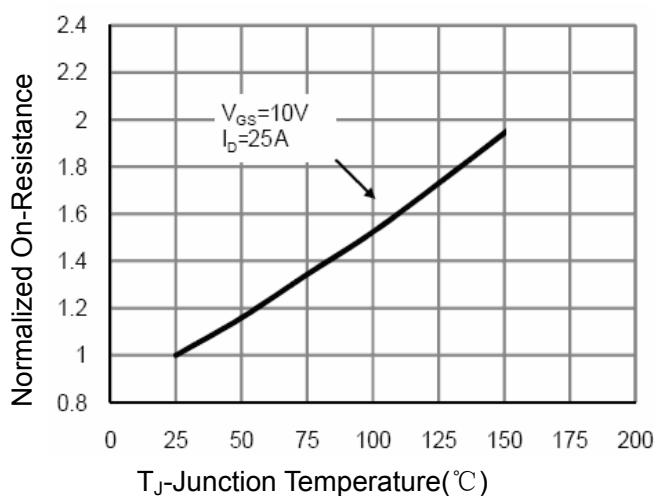


Figure 4 Rdson-Junction Temperature

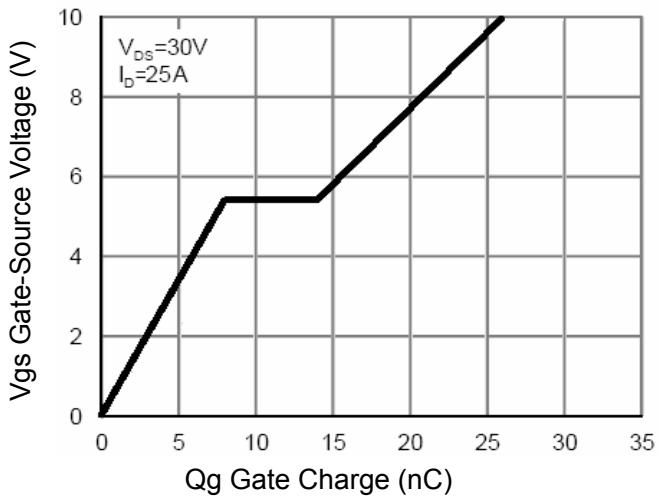


Figure 5 Gate Charge

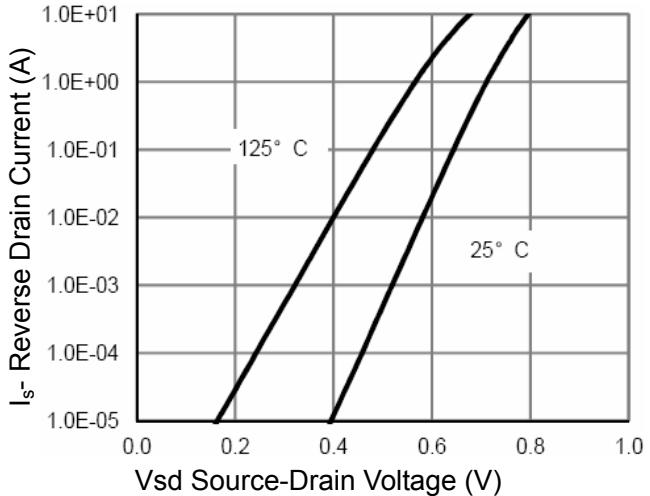


Figure 6 Source- Drain Diode Forward

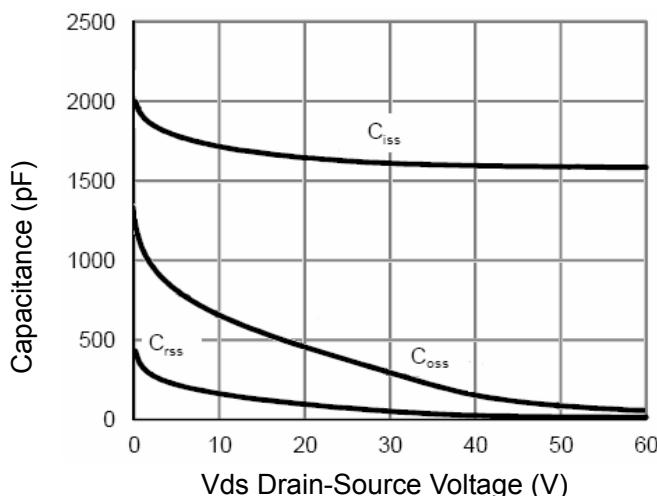


Figure 7 Capacitance vs Vds

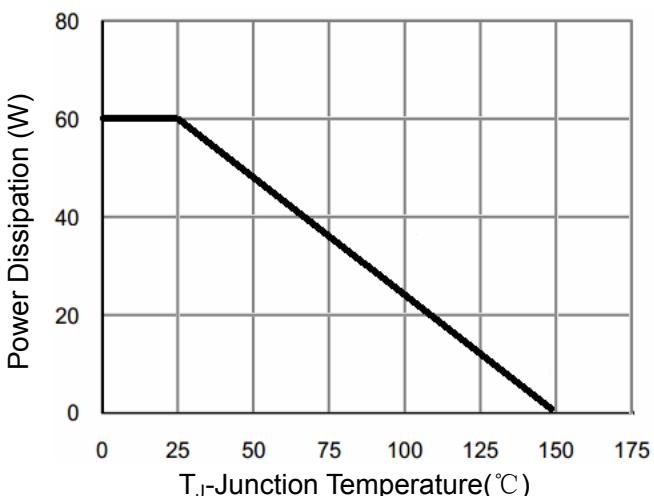


Figure 9 Power De-rating

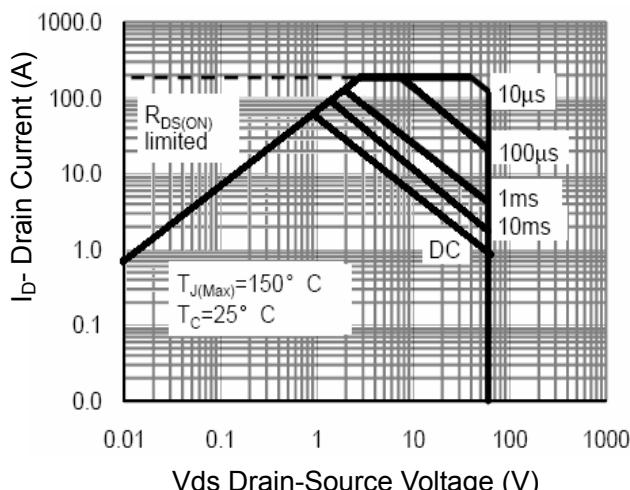


Figure 8 Safe Operation Area

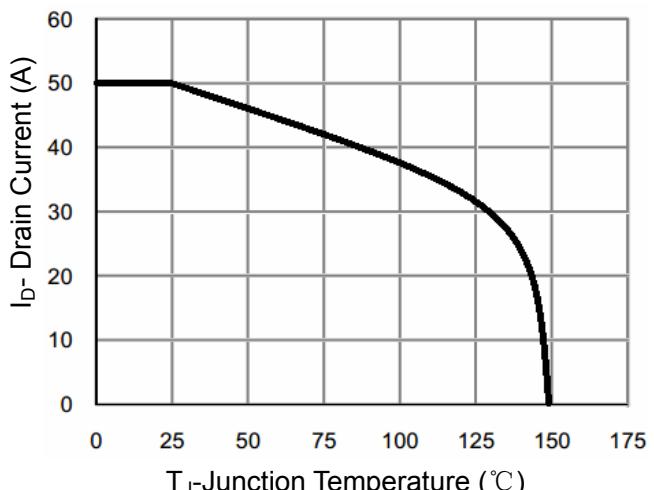


Figure 10 Current De-rating

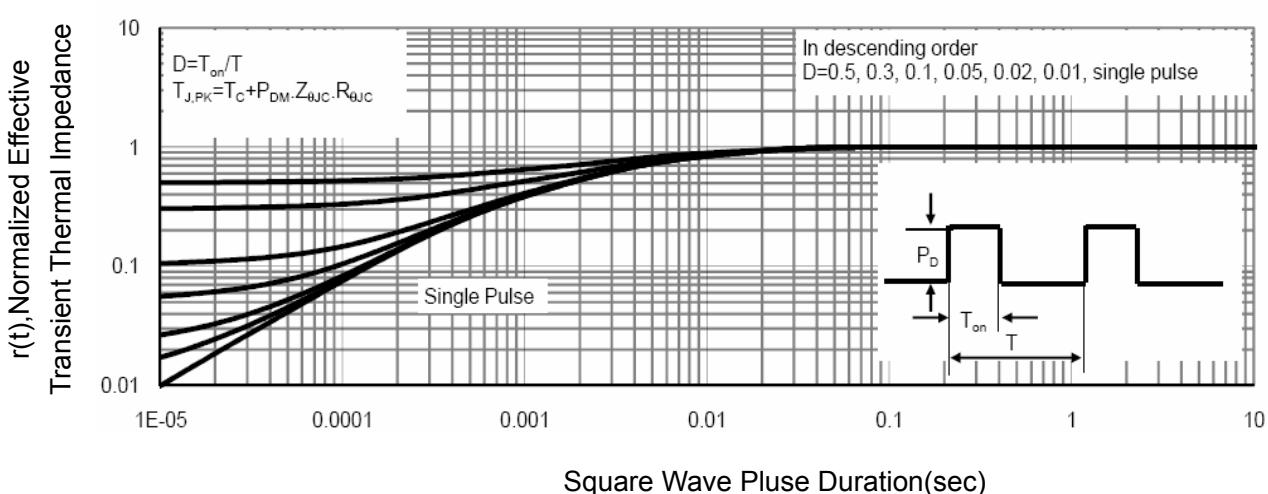
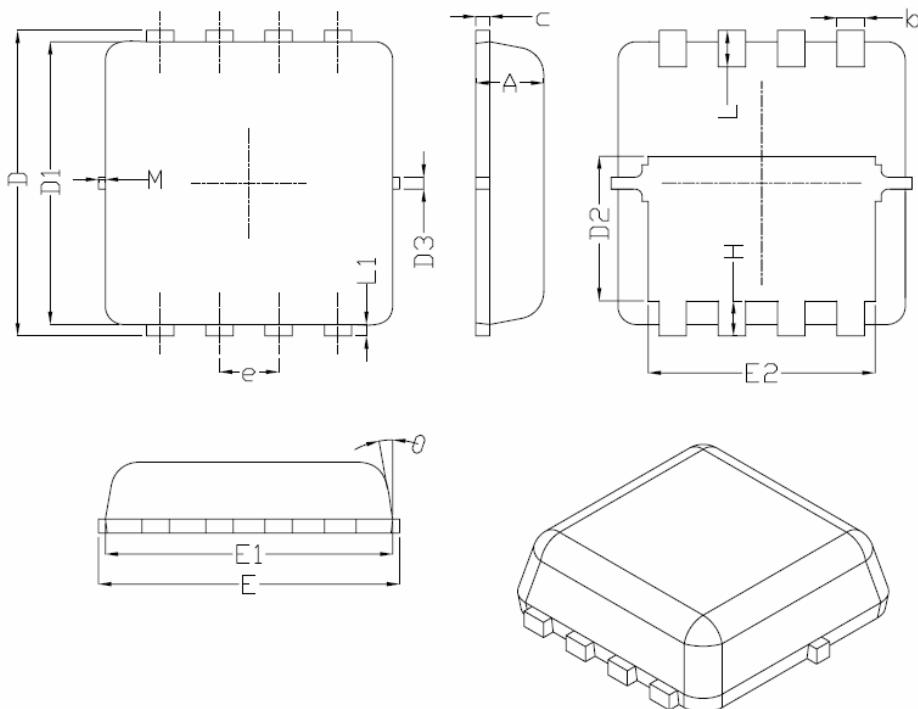


Figure 11 Normalized Maximum Transient Thermal Impedance

## **DFN3.3X3.3-8L Package Information**



Symbol	Dimensions In Millimeters		
	Min.	Nom.	Max.
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.48	1.58	1.68
D3	-	0.13	-
E	3.20	3.30	3.40
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
e	0.65BSC		
H	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	-	0.13	-
M	*	*	0.15
θ		10°	12°

Land Pattern  
(Only for Reference)

